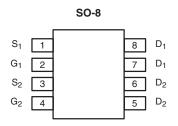


Dual P-Channel 20V (D-S) MOSFET

| PRODUCT SUMMARY | | | | |
|---------------------|------------------------------------|--------------------|--|--|
| V _{DS} (V) | $R_{DS(on)}\left(\Omega\right)$ | I _D (A) | | |
| | 0.018 at V _{GS} = - 4.5 V | - 8.9 | | |
| - 20 | 0.022 at V _{GS} = - 2.5 V | - 8.1 | | |
| | 0.030 at V _{GS} = - 1.8 V | - 3.6 | | |



FEATURES

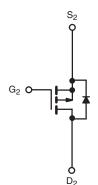
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Advanced High Cell Density Process
- Compliant to RoHS Directive 2002/95/EC

Pb-free ROHS COMPLIANT HALOGEN FREE Available

APPLICATIONS

• Load Switching

G₁



P-Channel MOSFET

P-Channel MOSFET

| ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted | | | | | | |
|---|------------------------|-----------------------------------|-------------|--------------|------|--|
| Parameter | | Symbol | 10 s | Steady State | Unit | |
| Drain-Source Voltage | | V _{DS} | - 20 | | V | |
| Gate-Source Voltage | | V _{GS} | ± 12 | | | |
| Continuous Drain Current /T 150 °C\8 | T _A = 25 °C | - I _D | - 8.9 | - 6.7 | | |
| Continuous Drain Current (T _J = 150 °C) ^a | T _A = 70 °C | | - 7.1 | - 5.4 | | |
| Pulsed Drain Current | | I _{DM} | - 30 | | Α | |
| Continuous Source Current (Diode Conduction) ^a | | I _S | - 1.7 | - 0.9 | | |
| | T _A = 25 °C | - P _D | 2.0 | 1.1 | W | |
| Maximum Power Dissipation ^a | T _A = 70 °C |] ' ['] D | 1.3 | 0.7 |] | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 to 150 | | °C | |

| THERMAL RESISTANCE RATINGS | | | | | |
|--|--------------|-------------------|---------|---------|------|
| Parameter | | Symbol | Typical | Maximum | Unit |
| Maniana landian ta Ankinda | t ≤ 10 s | R _{thJA} | 46 | 62.5 | |
| Maximum Junction-to-Ambient ^a | Steady State | □thJA | 80 | 110 | °C/W |
| Maximum Junction-to-Foot (Drain) | Steady State | R_{thJF} | 24 | 32 | |

Notes:

a. Surface Mounted on 1" x 1" FR4 board.



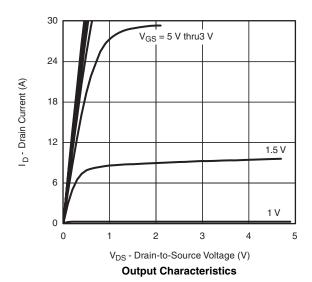
| Parameter | Symbol Test Conditions | | Min. | Тур. | Max. | Unit | |
|---|------------------------|---|-------|-------|-------|------|--|
| Static | | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = -350 \mu A$ | - 0.4 | | - 1.0 | V | |
| Gate-Body Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$ | | | ± 100 | nA | |
| Zana Cata Valtana Busin Comunit | | V _{DS} = - 20 V, V _{GS} = 0 V | | | - 1 | μΑ | |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C | | | - 5 | | |
| On-State Drain Current ^a | I _{D(on)} | V _{DS} = - 5 V, V _{GS} = - 4.5 V - 30 | | | | Α | |
| | | V _{GS} = - 4.5 V, I _D = - 8.9 A | | 0.018 | | Ω | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | V _{GS} = - 2.5 V, I _D = - 8.1 A | | 0.022 | | | |
| | | V _{GS} = - 1.8 V, I _D = - 3.6 A | | 0.030 | | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = - 10 V, I _D = - 8.9 A | | 26 | | S | |
| Diode Forward Voltage ^a | V_{SD} | I _S = - 1.7 A, V _{GS} = 0 V | | - 0.7 | - 1.2 | V | |
| Dynamic ^b | | | | | | | |
| Total Gate Charge | Q_g | | | 34.5 | 52 | | |
| Gate-Source Charge | Q _{gs} | V _{DS} = - 10 V, V _{GS} = - 4.5 V, I _D = - 8.9 A | | 5.1 | | nC | |
| Gate-Drain Charge | Q_{gd} | 1 | | 9.6 | | | |
| Gate Resistance | R_g | | | 9 | | Ω | |
| Turn-On Delay Time | t _{d(on)} | | | 25 | 40 | ns | |
| Rise Time | t _r | V_{DD} = - 10 V, R_L = 6 Ω | | 46 | 70 | | |
| Turn-Off Delay Time | t _{d(off)} | $I_D \cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 6 Ω | | 230 | 345 | | |
| Fall Time | t _f | | | 155 | 235 | | |
| Source-Drain Reverse Recovery Time | t _{rr} | I _F = - 1.7 A, dl/dt = 100 A/μs | | 128 | 200 | | |

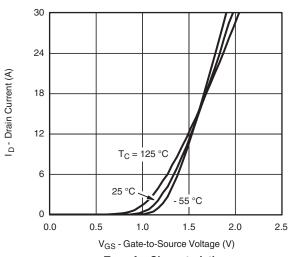
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C unless otherwise noted





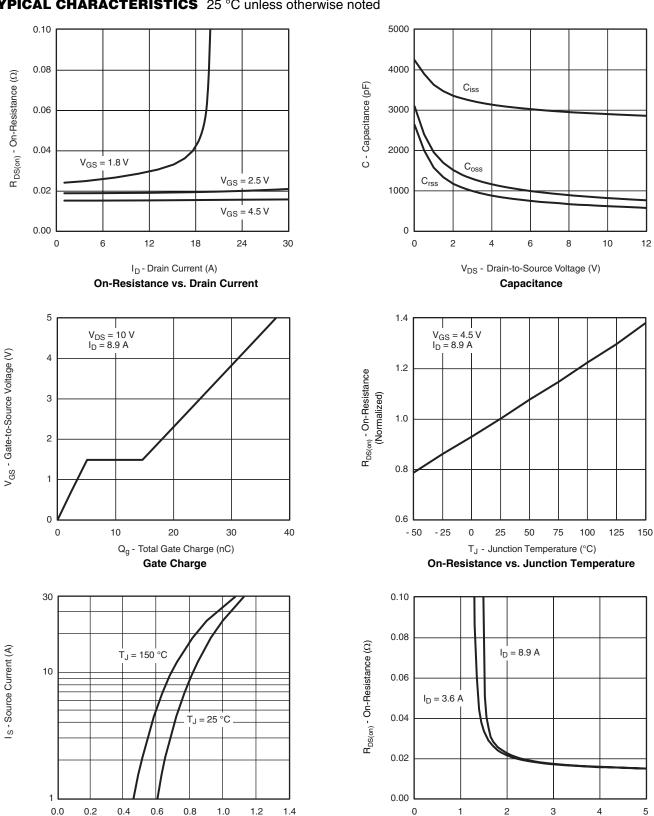
Transfer Characteristics



TYPICAL CHARACTERISTICS 25 °C unless otherwise noted

V_{SD} - Source-to-Drain Voltage (V)

Source-Drain Diode Forward Voltage



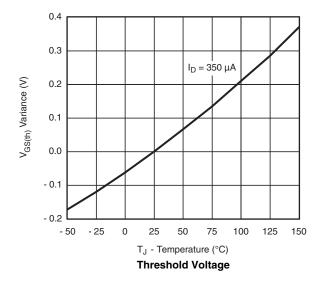
 V_{GS} - Gate-to-Source Voltage (V)

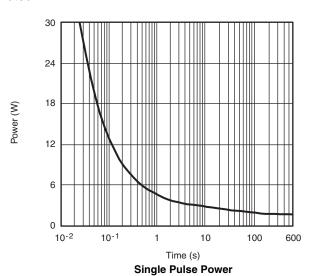
On-Resistance vs. Gate-to-Source Voltage

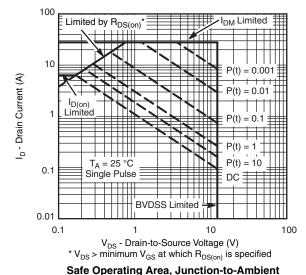
Normalized Effective Transient Thermal Impedance

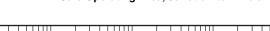


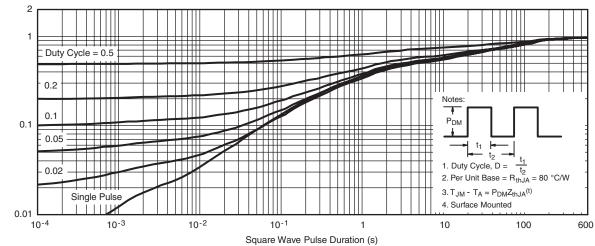
TYPICAL CHARACTERISTICS 25 °C unless otherwise noted









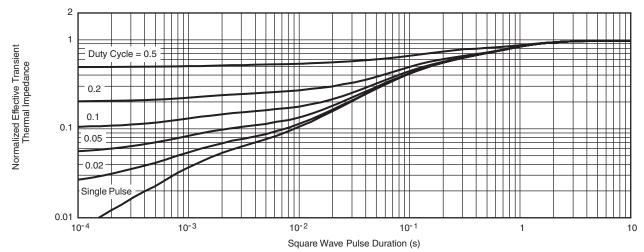


Normalized Thermal Transient Impedance, Junction-to-Ambient

4



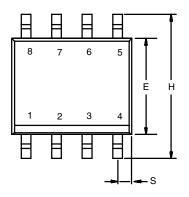
TYPICAL CHARACTERISTICS 25 °C unless otherwise noted

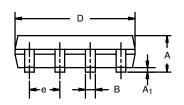


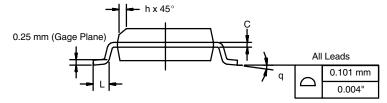
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







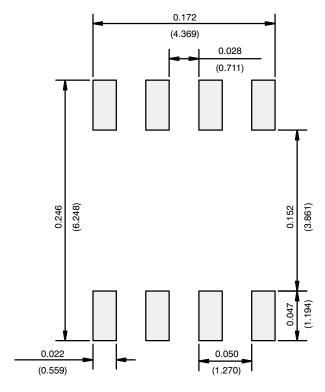
| | MILLIM | IETERS | INCHES | | | |
|------------------------------|----------|--------|-----------|-------|--|--|
| DIM | Min | Max | Min | Max | | |
| Α | 1.35 | 1.75 | 0.053 | 0.069 | | |
| A ₁ | 0.10 | 0.20 | 0.004 | 0.008 | | |
| В | 0.35 | 0.51 | 0.014 | 0.020 | | |
| С | 0.19 | 0.25 | 0.0075 | 0.010 | | |
| D | 4.80 | 5.00 | 0.189 | 0.196 | | |
| E | 3.80 | 4.00 | 0.150 | 0.157 | | |
| е | 1.27 BSC | | 0.050 BSC | | | |
| Н | 5.80 | 6.20 | 0.228 | 0.244 | | |
| h | 0.25 | 0.50 | 0.010 | 0.020 | | |
| L | 0.50 | 0.93 | 0.020 | 0.037 | | |
| q | 0° | 8° | 0° | 8° | | |
| S | 0.44 | 0.64 | 0.018 | 0.026 | | |
| ECN: C 06527 Pay L 11 Cap 06 | | | | | | |

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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